

# SOT101-1

plastic dual in-line package; 24 leads (600 mil)

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	DIP24
<b>Package type industry code</b>	DIP24
<b>Package style descriptive code</b>	DIP (dual in-line package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	051G02
<b>JEDEC package outline code</b>	MO-015
<b>JEITA package outline code</b>	SC-509-24
<b>Mounting method type</b>	T (through-hole mount)
<b>Issue date</b>	13-2-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	31.4	-	31.7	32	mm
E	package width	13.7	-	13.8	14.1	mm
A	seated height	[tbd]	-	5.1	5.1	mm
A <sub>2</sub>	package height	[tbd]	-	3.85	4	mm
n <sub>2</sub>	actual quantity of termination	-	-	24	-	



## 2. Package outline

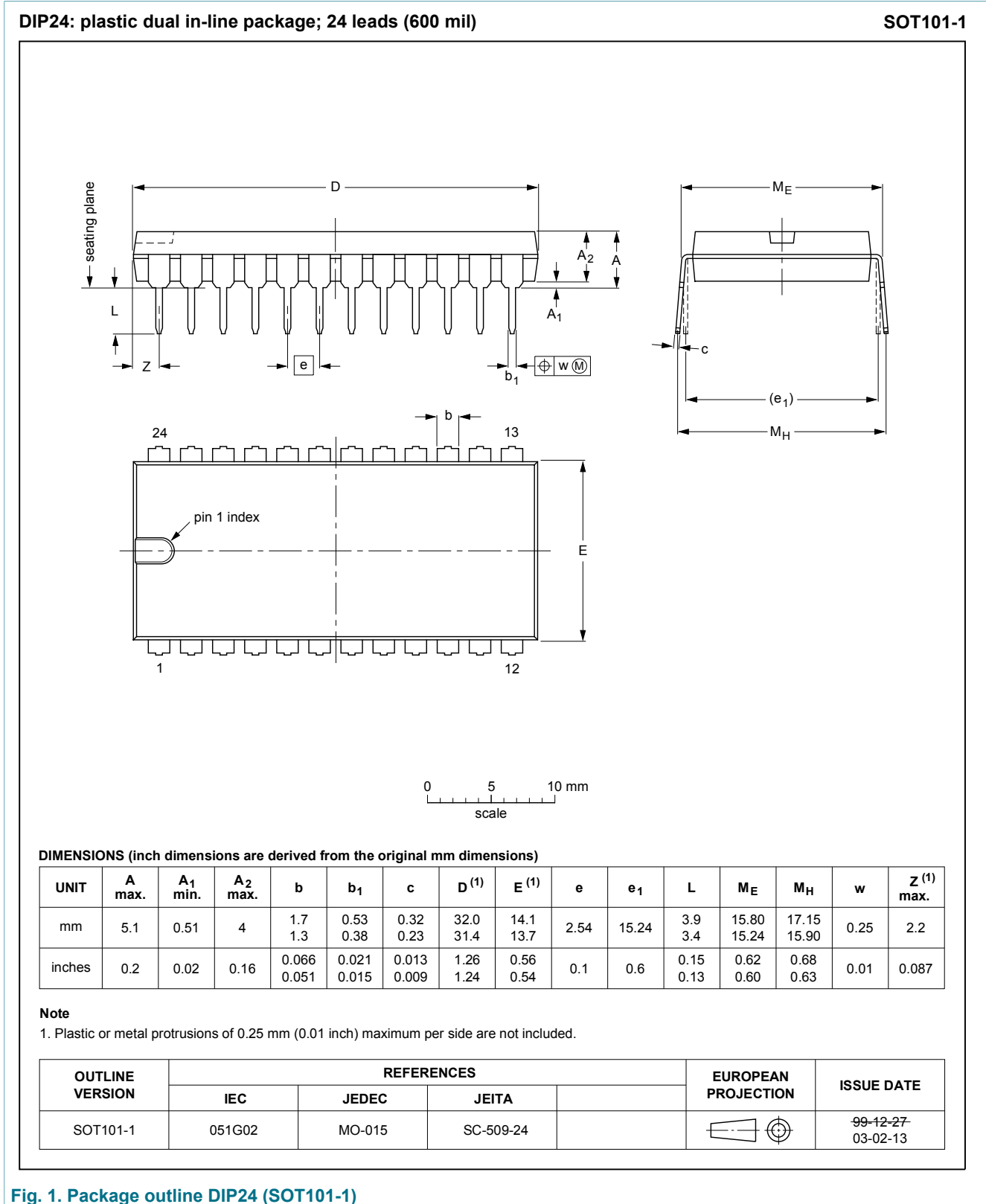


Fig. 1. Package outline DIP24 (SOT101-1)

### 3. Legal information

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Date of release: 8 February 2016

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